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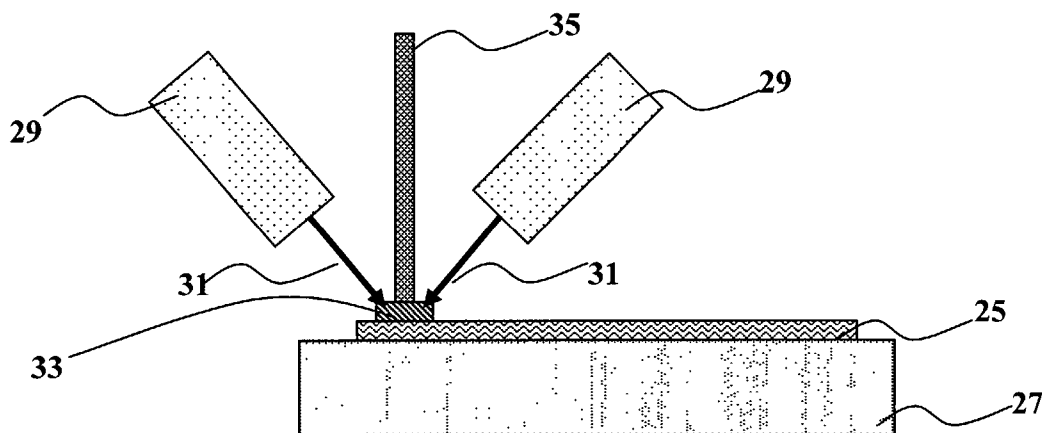
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ning of each regular issue of the PCT Gazette.

(54) Title: SEALING LIGHTING DEVICE COMPONENT ASSEMBLY WITH SOLDER GLASS PREFORM BY USING IN-
FRARED RADIATION



(57) Abstract: Disclosed is a method for sealing and affixing a component assembly for an electrical lighting device to a glass lamp envelope. The assembly used in the process comprises the component, such as an electrode lead wire and a solder glass preform. The process is useful, for example, in hermetically sealing and affixing lamp components, such as electrical lead wires and exhaust tubulation, to a low pressure fluorescent discharge lamp envelope having phosphor coating already applied thereto. The present invention is particularly suitable for lamp envelope made of borosilicate glass having a CTE from 0 to 300°C in the range of 30-45x10⁻⁷ °C⁻¹.

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